

DATA SHEET



PCF8591

8-bit A/D and D/A converter

Product specification
Supersedes data of 1997 Apr 02
File under Integrated Circuits, IC12

1998 Jul 02

8-bit A/D and D/A converter**PCF8591****CONTENTS**

1	FEATURES
2	APPLICATIONS
3	GENERAL DESCRIPTION
4	ORDERING INFORMATION
5	BLOCK DIAGRAM
6	PINNING
7	FUNCTIONAL DESCRIPTION
7.1	Addressing
7.2	Control byte
7.3	D/A conversion
7.4	A/D conversion
7.5	Reference voltage
7.6	Oscillator
8	CHARACTERISTICS OF THE I ² C-BUS
8.1	Bit transfer
8.2	Start and stop conditions
8.3	System configuration
8.4	Acknowledge
8.5	I ² C-bus protocol
9	LIMITING VALUES
10	HANDLING
11	DC CHARACTERISTICS
12	D/A CHARACTERISTICS
13	A/D CHARACTERISTICS
14	AC CHARACTERISTICS
15	APPLICATION INFORMATION
16	PACKAGE OUTLINES
17	SOLDERING
17.1	Introduction
17.2	DIP
17.2.1	Soldering by dipping or by wave
17.2.2	Repairing soldered joints
17.3	SO
17.3.1	Reflow soldering
17.3.2	Wave soldering
17.3.3	Repairing soldered joints
18	DEFINITIONS
19	LIFE SUPPORT APPLICATIONS
20	PURCHASE OF PHILIPS I ² C COMPONENTS

8-bit A/D and D/A converter

PCF8591

1 FEATURES

- Single power supply
- Operating supply voltage 2.5 V to 6 V
- Low standby current
- Serial input/output via I²C-bus
- Address by 3 hardware address pins
- Sampling rate given by I²C-bus speed
- 4 analog inputs programmable as single-ended or differential inputs
- Auto-incremented channel selection
- Analog voltage range from V_{SS} to V_{DD}
- On-chip track and hold circuit
- 8-bit successive approximation A/D conversion
- Multiplying DAC with one analog output.

2 APPLICATIONS

- Closed loop control systems
- Low power converter for remote data acquisition
- Battery operated equipment
- Acquisition of analog values in automotive, audio and TV applications.

4 ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PCA8591P	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1
PCA8591T	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1

**3 GENERAL DESCRIPTION**

The PCF8591 is a single-chip, single-supply low power 8-bit CMOS data acquisition device with four analog inputs, one analog output and a serial I²C-bus interface. Three address pins A0, A1 and A2 are used for programming the hardware address, allowing the use of up to eight devices connected to the I²C-bus without additional hardware. Address, control and data to and from the device are transferred serially via the two-line bidirectional I²C-bus.

The functions of the device include analog input multiplexing, on-chip track and hold function, 8-bit analog-to-digital conversion and an 8-bit digital-to-analog conversion. The maximum conversion rate is given by the maximum speed of the I²C-bus.

8-bit A/D and D/A converter

PCF8591

5 BLOCK DIAGRAM

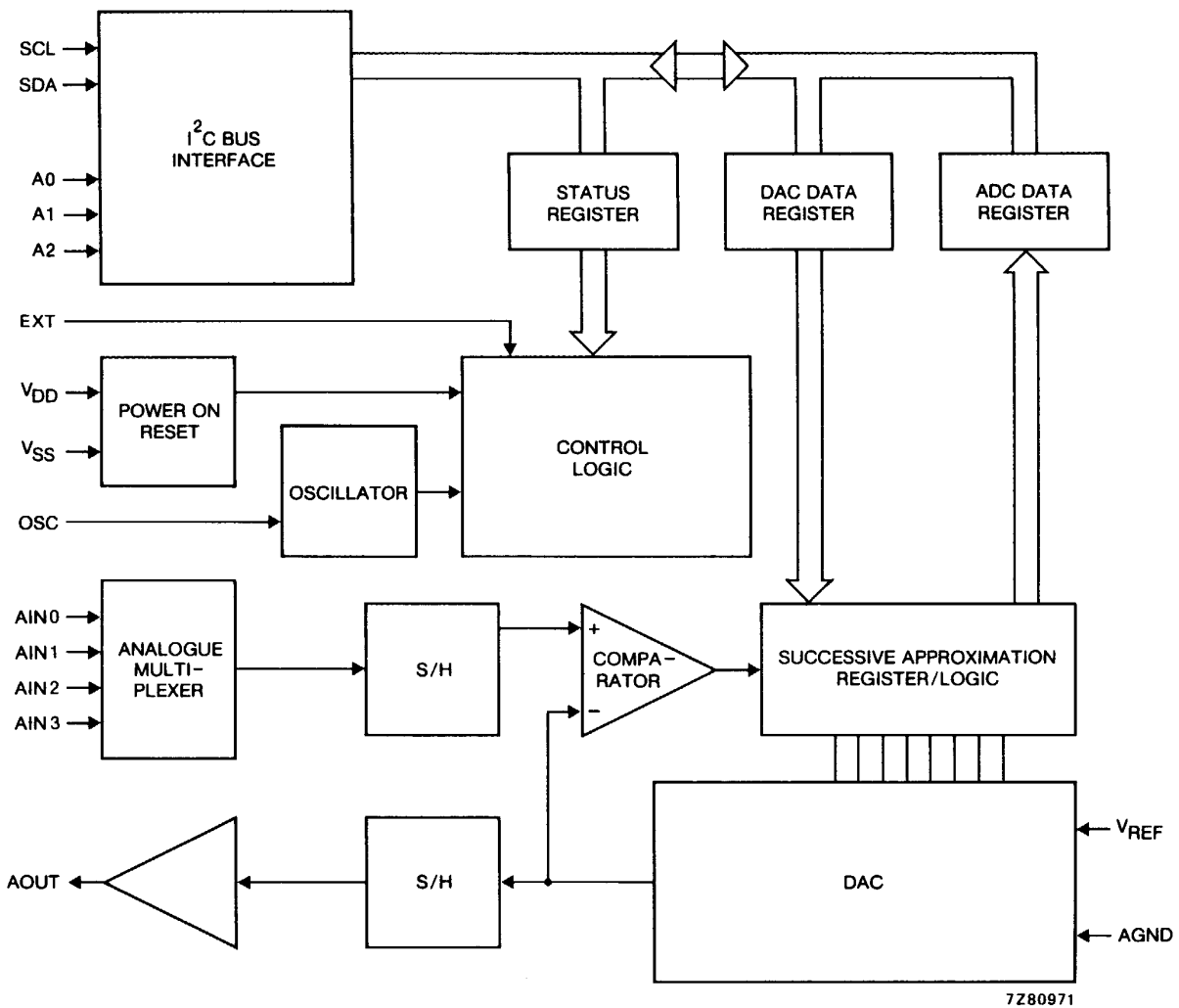


Fig.1 Block diagram.

8-bit A/D and D/A converter

PCF8591

6 PINNING

SYMBOL	PIN	DESCRIPTION
AIN0	1	analog inputs (A/D converter)
AIN1	2	
AIN2	3	
AIN3	4	
A0	5	hardware address
A1	6	
A2	7	
V _{SS}	8	
SDA	9	I ² C-bus data input/output
SCL	10	I ² C-bus clock input
OSC	11	oscillator input/output
EXT	12	external/internal switch for oscillator input
AGND	13	analog ground
V _{REF}	14	voltage reference input
AOUT	15	analog output (D/A converter)
V _{DD}	16	positive supply voltage

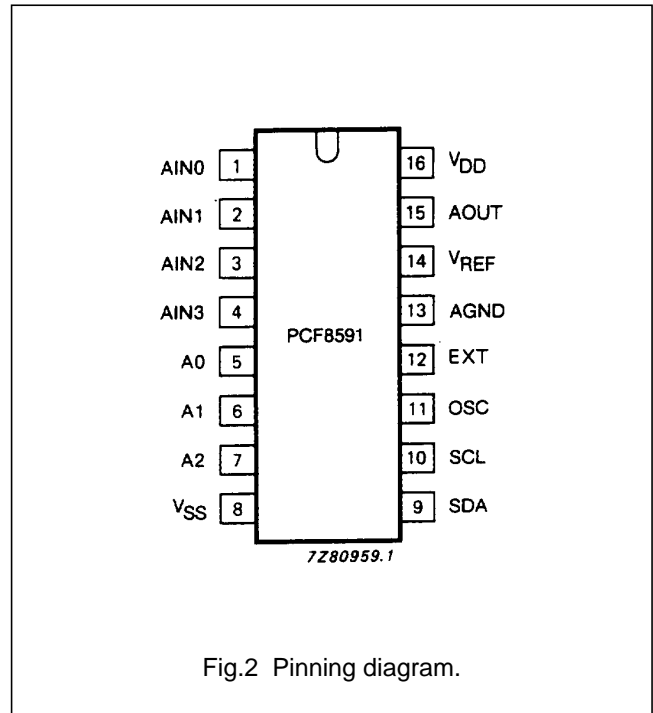


Fig.2 Pinning diagram.

8-bit A/D and D/A converter

PCF8591

7 FUNCTIONAL DESCRIPTION

7.1 Addressing

Each PCF8591 device in an I²C-bus system is activated by sending a valid address to the device. The address consists of a fixed part and a programmable part. The programmable part must be set according to the address pins A0, A1 and A2. The address always has to be sent as the first byte after the start condition in the I²C-bus protocol. The last bit of the address byte is the read/write-bit which sets the direction of the following data transfer (see Figs 3, 15 and 16).

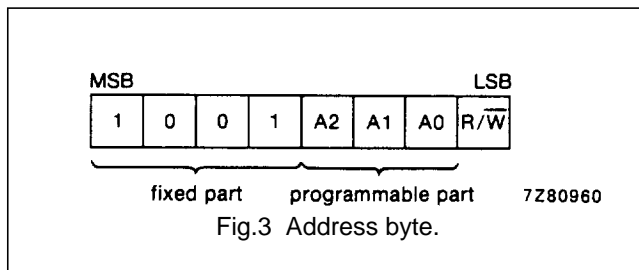


Fig.3 Address byte.

7.2 Control byte

The second byte sent to a PCF8591 device will be stored in its control register and is required to control the device function.

The upper nibble of the control register is used for enabling the analog output, and for programming the analog inputs as single-ended or differential inputs. The lower nibble selects one of the analog input channels defined by the upper nibble (see Fig.4). If the auto-increment flag is set the channel number is incremented automatically after each A/D conversion.

If the auto-increment mode is desired in applications where the internal oscillator is used, the analog output enable flag in the control byte (bit 6) should be set. This allows the internal oscillator to run continuously, thereby preventing conversion errors resulting from oscillator start-up delay. The analog output enable flag may be reset at other times to reduce quiescent power consumption.

The selection of a non-existing input channel results in the highest available channel number being allocated. Therefore, if the auto-increment flag is set, the next selected channel will be always channel 0. The most significant bits of both nibbles are reserved for future functions and have to be set to 0. After a Power-on reset condition all bits of the control register are reset to 0. The D/A converter and the oscillator are disabled for power saving. The analog output is switched to a high-impedance state.

8-bit A/D and D/A converter

PCF8591

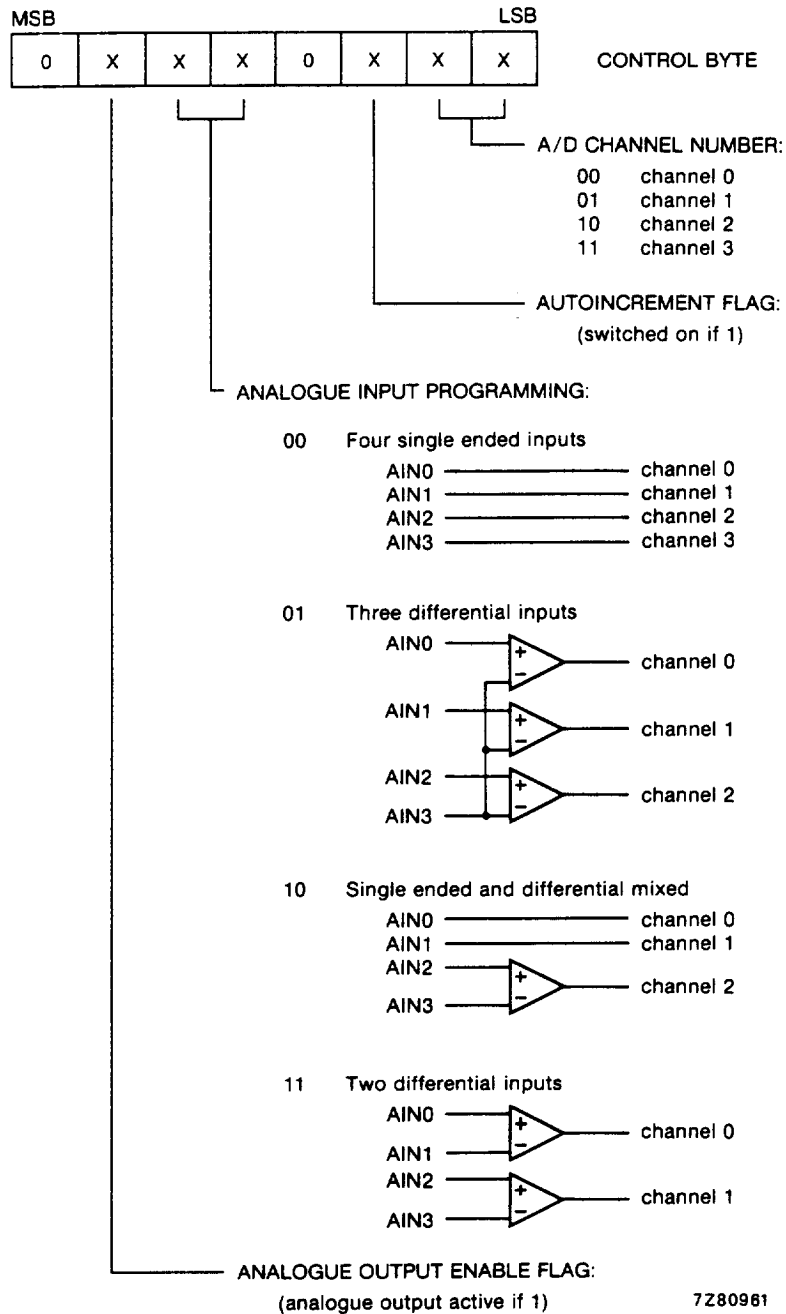


Fig.4 Control byte.

8-bit A/D and D/A converter

PCF8591

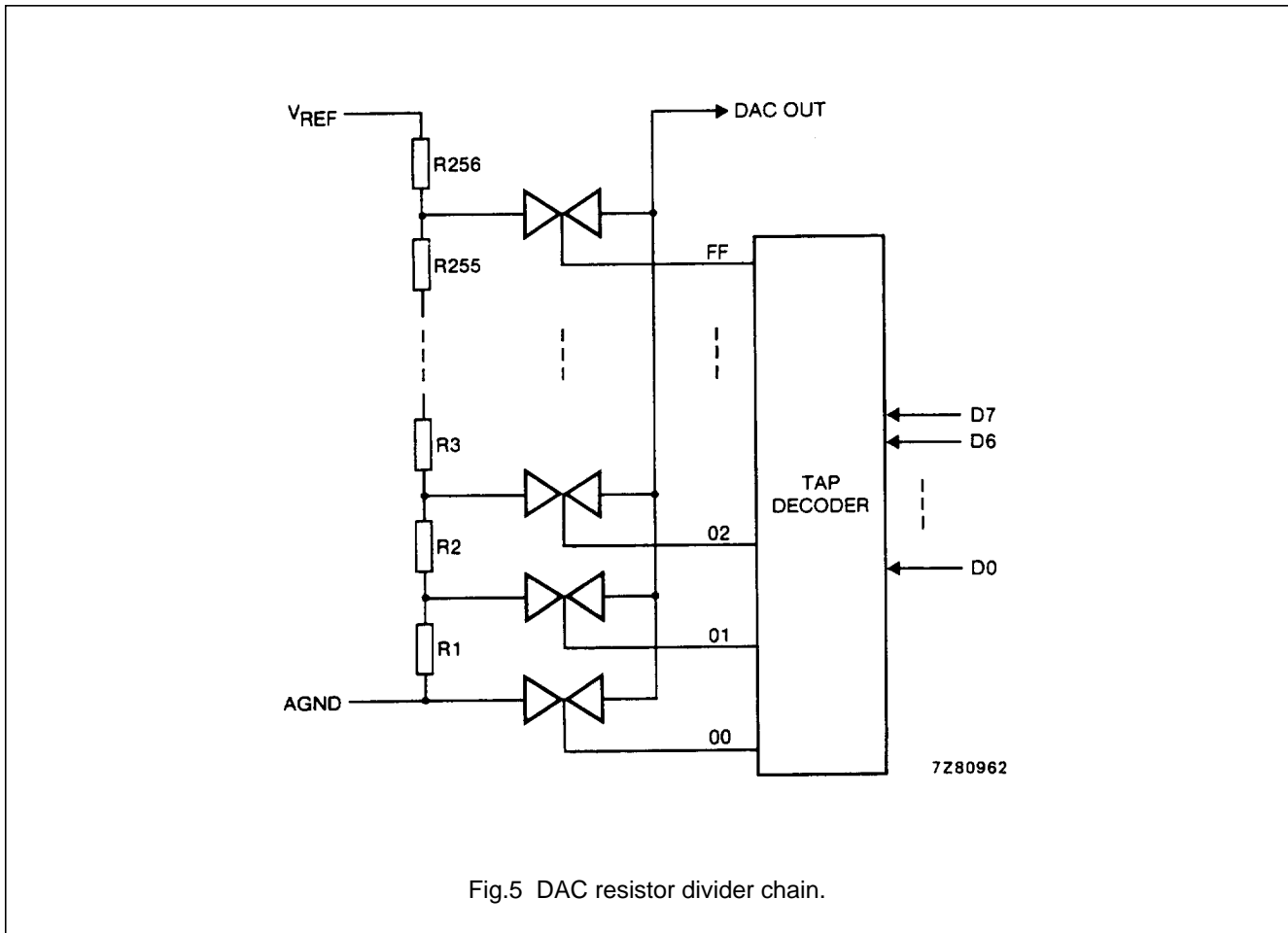
7.3 D/A conversion

The third byte sent to a PCF8591 device is stored in the DAC data register and is converted to the corresponding analog voltage using the on-chip D/A converter. This D/A converter consists of a resistor divider chain connected to the external reference voltage with 256 taps and selection switches. The tap-decoder switches one of these taps to the DAC output line (see Fig.5).

The analog output voltage is buffered by an auto-zeroed unity gain amplifier. This buffer amplifier may be switched on or off by setting the analog output enable flag of the control register. In the active state the output voltage is held until a further data byte is sent.

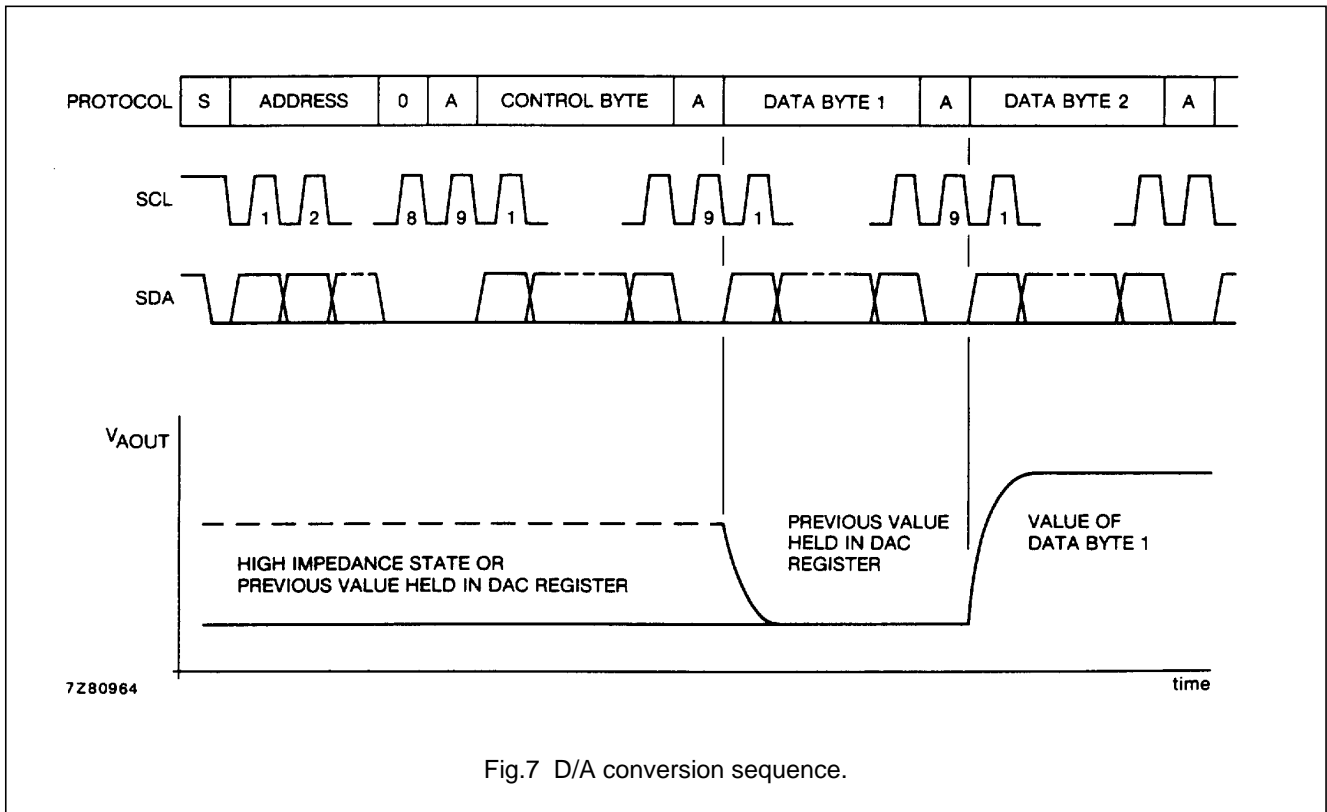
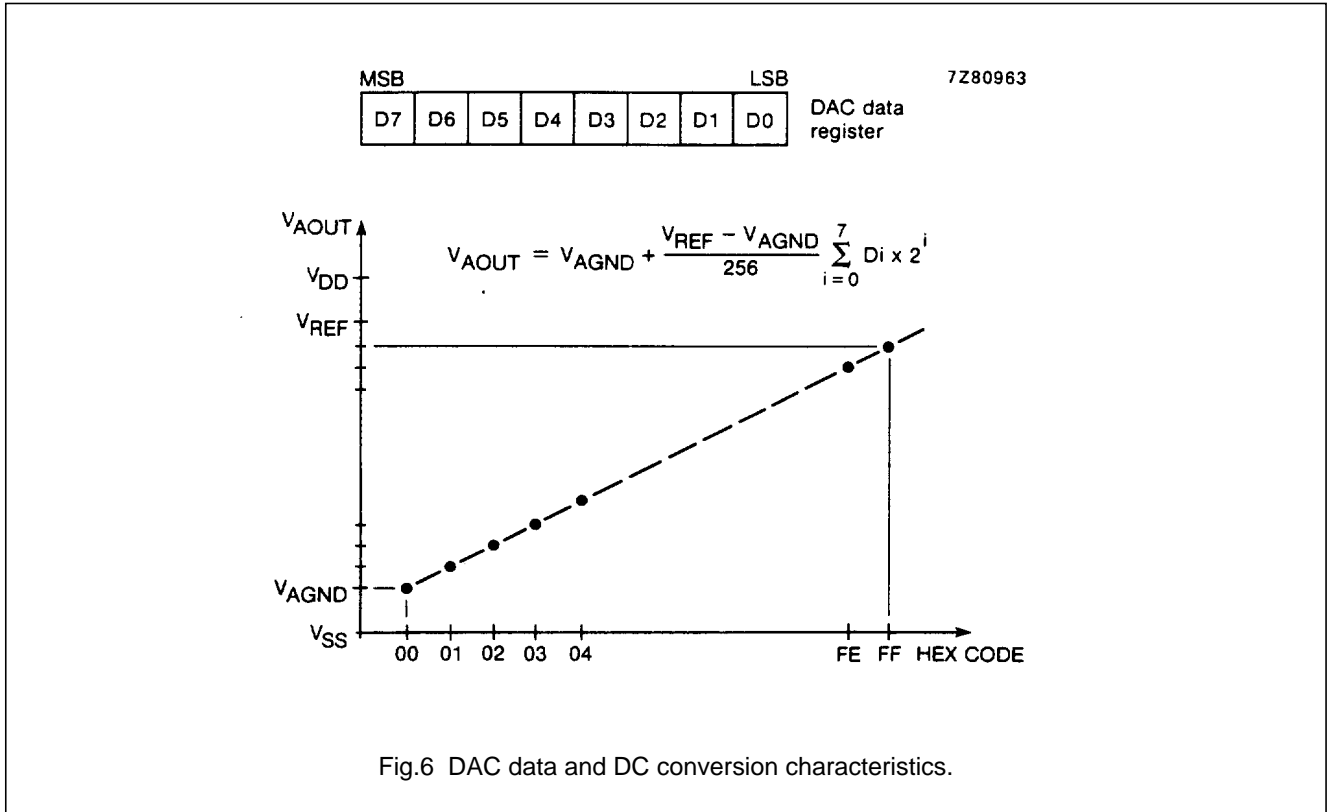
The on-chip D/A converter is also used for successive approximation A/D conversion. In order to release the DAC for an A/D conversion cycle the unity gain amplifier is equipped with a track and hold circuit. This circuit holds the output voltage while executing the A/D conversion.

The output voltage supplied to the analog output AOUT is given by the formula shown in Fig.6. The waveforms of a D/A conversion sequence are shown in Fig.7.



8-bit A/D and D/A converter

PCF8591



8-bit A/D and D/A converter

PCF8591

7.4 A/D conversion

The A/D converter makes use of the successive approximation conversion technique. The on-chip D/A converter and a high-gain comparator are used temporarily during an A/D conversion cycle.

An A/D conversion cycle is always started after sending a valid read mode address to a PCF8591 device. The A/D conversion cycle is triggered at the trailing edge of the acknowledge clock pulse and is executed while transmitting the result of the previous conversion (see Fig.8).

Once a conversion cycle is triggered an input voltage sample of the selected channel is stored on the chip and is converted to the corresponding 8-bit binary code. Samples picked up from differential inputs are converted to an 8-bit two's complement code (see Figs 9 and 10).

The conversion result is stored in the ADC data register and awaits transmission. If the auto-increment flag is set the next channel is selected.

The first byte transmitted in a read cycle contains the conversion result code of the previous read cycle. After a Power-on reset condition the first byte read is a hexadecimal 80. The protocol of an I²C-bus read cycle is shown in Chapter 8, Figs 15 and 16.

The maximum A/D conversion rate is given by the actual speed of the I²C-bus.

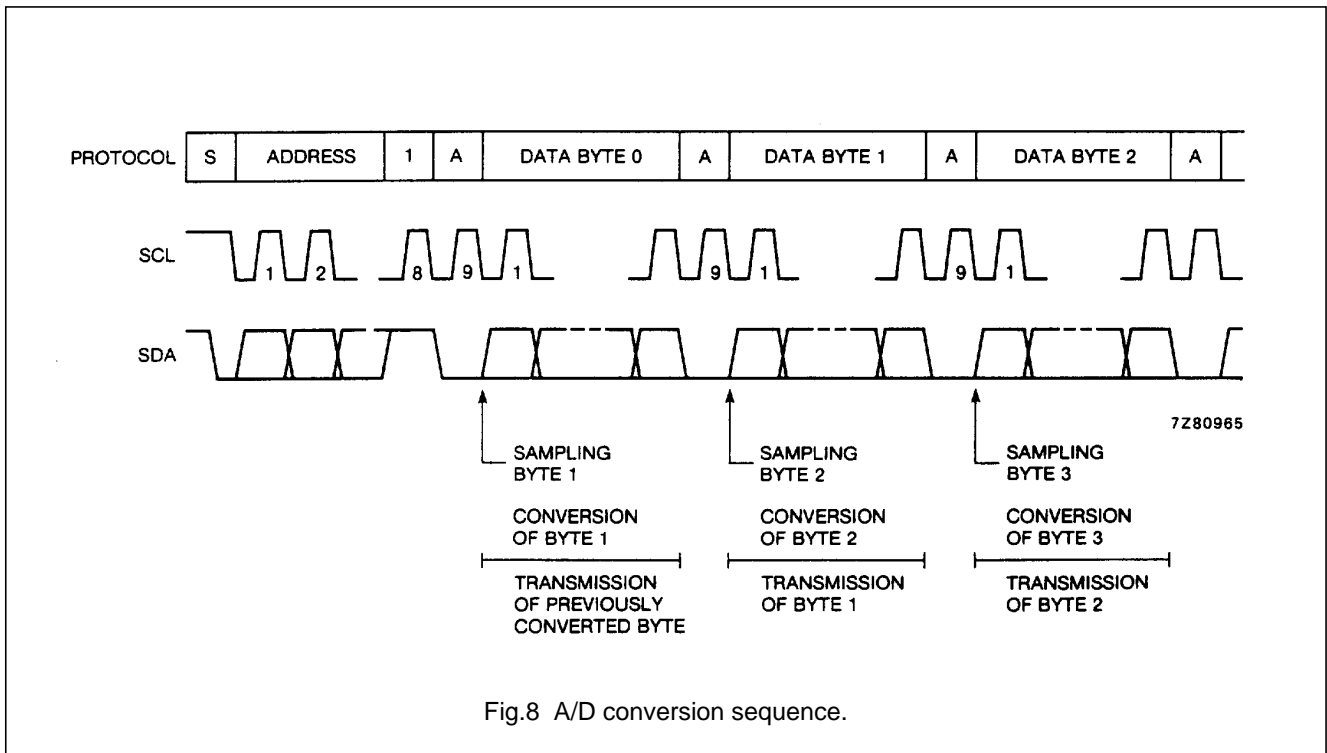


Fig.8 A/D conversion sequence.

8-bit A/D and D/A converter

PCF8591

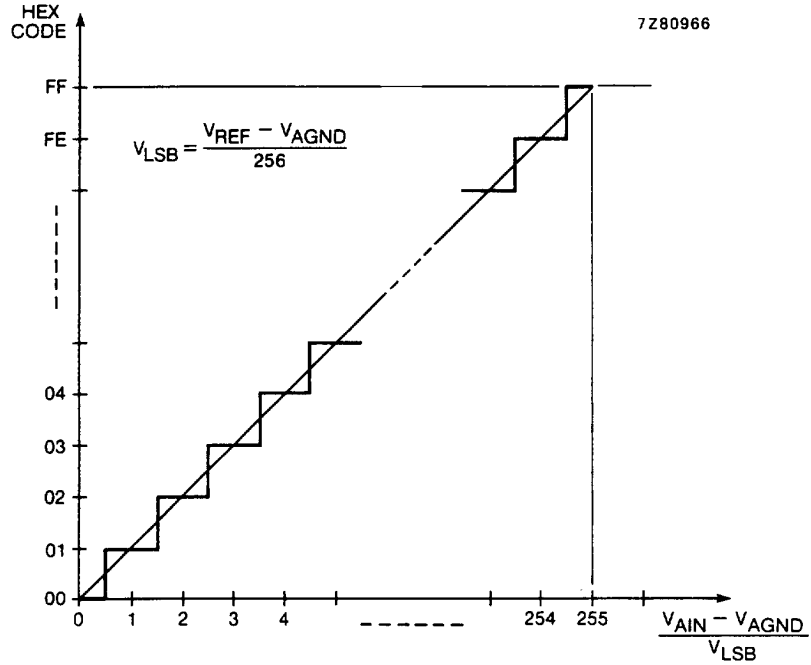


Fig.9 A/D conversion characteristics of single-ended inputs.

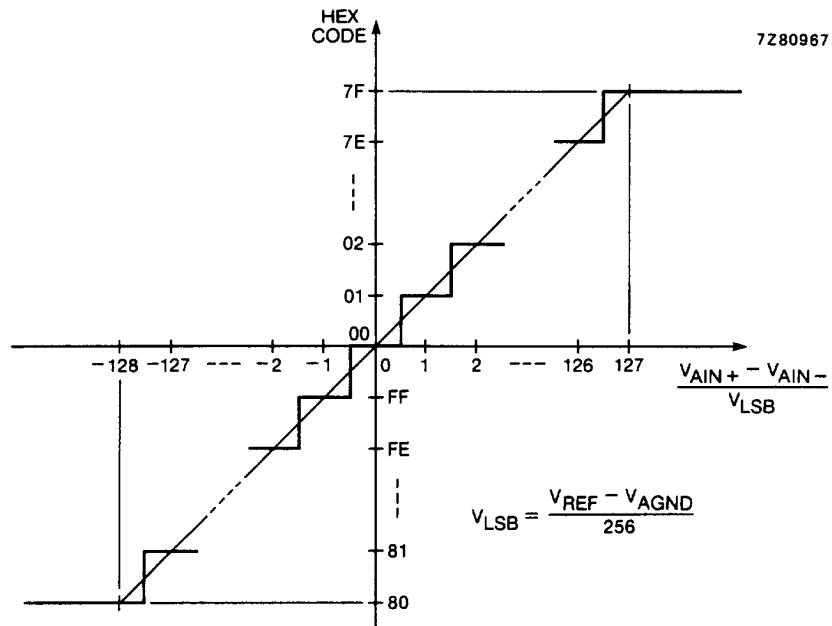


Fig.10 A/D conversion characteristics of differential inputs.

8-bit A/D and D/A converter

PCF8591

7.5 Reference voltage

For the D/A and A/D conversion either a stable external voltage reference or the supply voltage has to be applied to the resistor divider chain (pins V_{REF} and AGND).

The AGND pin has to be connected to the system analog ground and may have a DC off-set with reference to V_{SS} .

A low frequency may be applied to the V_{REF} and AGND pins. This allows the use of the D/A converter as a one-quadrant multiplier; see Chapter 15 and Fig.6.

The A/D converter may also be used as a one or two quadrant analog divider. The analog input voltage is divided by the reference voltage. The result is converted to a binary code. In this application the user has to keep the reference voltage stable during the conversion cycle.

7.6 Oscillator

An on-chip oscillator generates the clock signal required for the A/D conversion cycle and for refreshing the auto-zeroed buffer amplifier. When using this oscillator the EXT pin has to be connected to V_{SS} . At the OSC pin the oscillator frequency is available.

If the EXT pin is connected to V_{DD} the oscillator output OSC is switched to a high-impedance state allowing the user to feed an external clock signal to OSC.

8-bit A/D and D/A converter

PCF8591

8 CHARACTERISTICS OF THE I²C-BUS

The I²C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor. Data transfer may be initiated only when the bus is not busy.

8.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as a control signal.

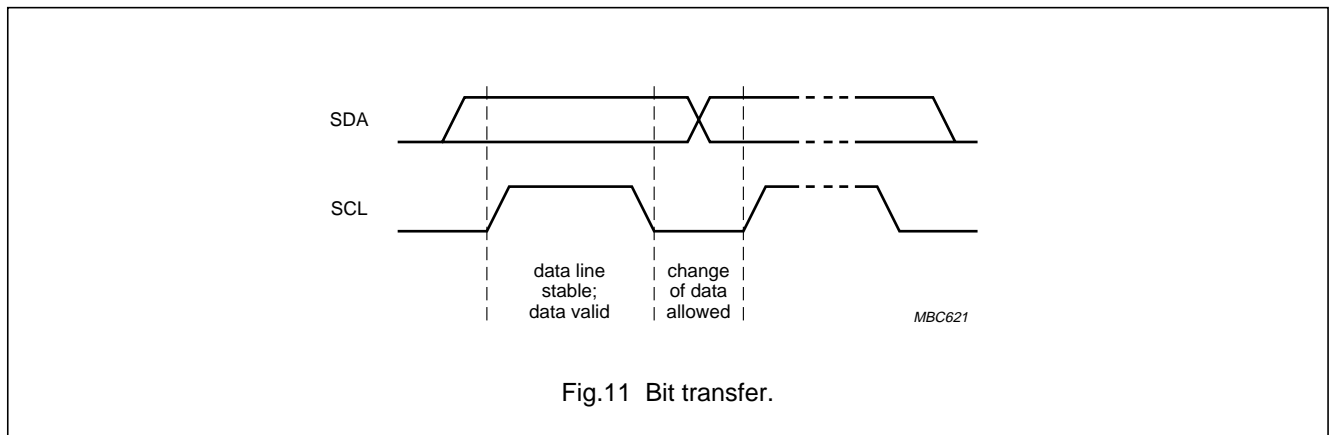


Fig.11 Bit transfer.

8.2 Start and stop conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH, is defined as the start condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH, is defined as the stop condition (P).

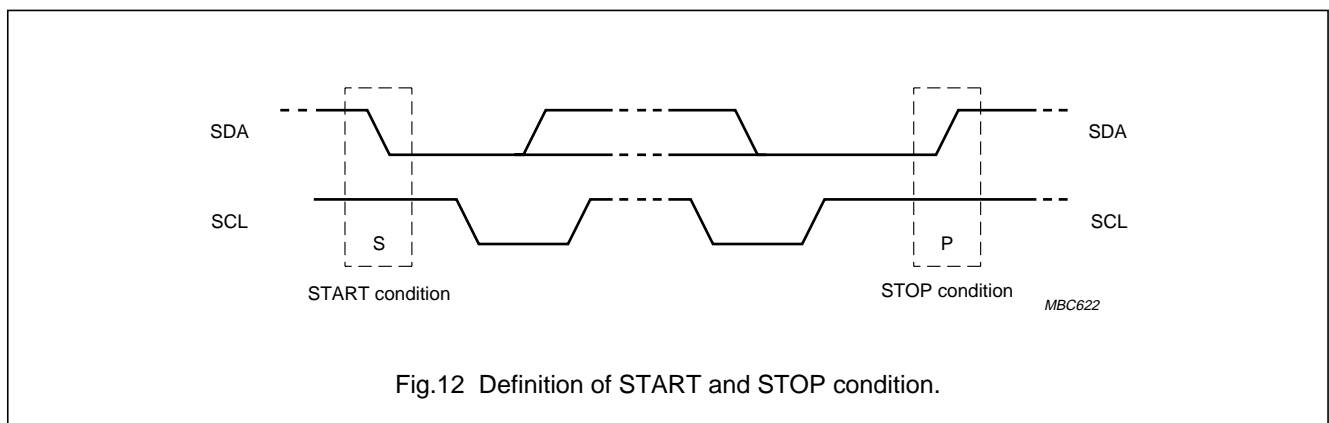


Fig.12 Definition of START and STOP condition.

8-bit A/D and D/A converter

PCF8591

8.3 System configuration

A device generating a message is a 'transmitter', a device receiving a message is the 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves'.

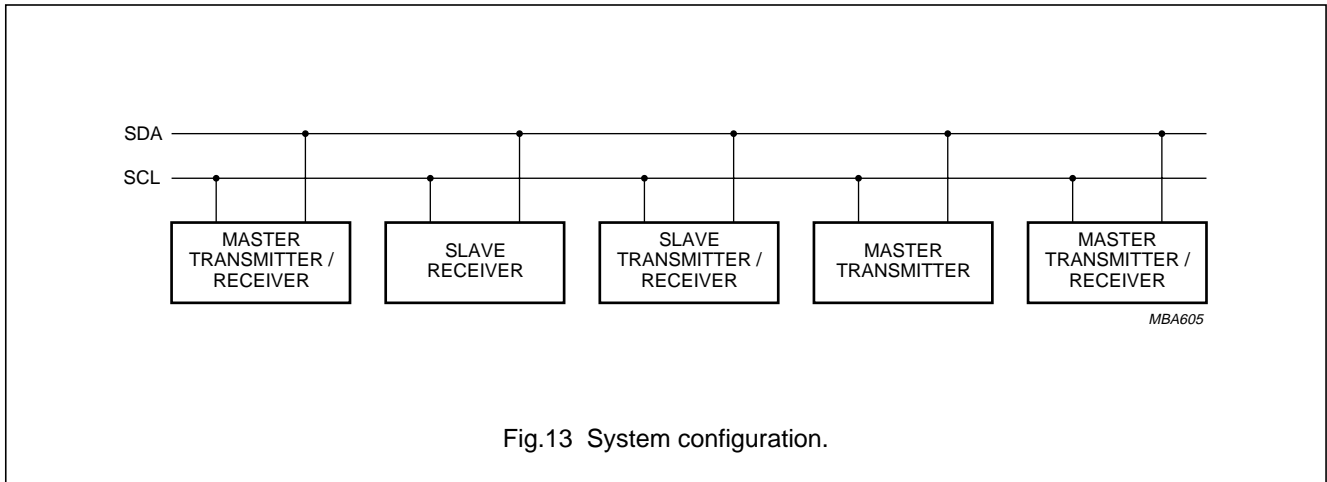


Fig.13 System configuration.

8.4 Acknowledge

The number of data bytes transferred between the start and stop conditions from transmitter to receiver is not limited. Each data byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter whereas the master also generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. A master receiver must signal an end of data to the transmitter by **not** generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a stop condition.

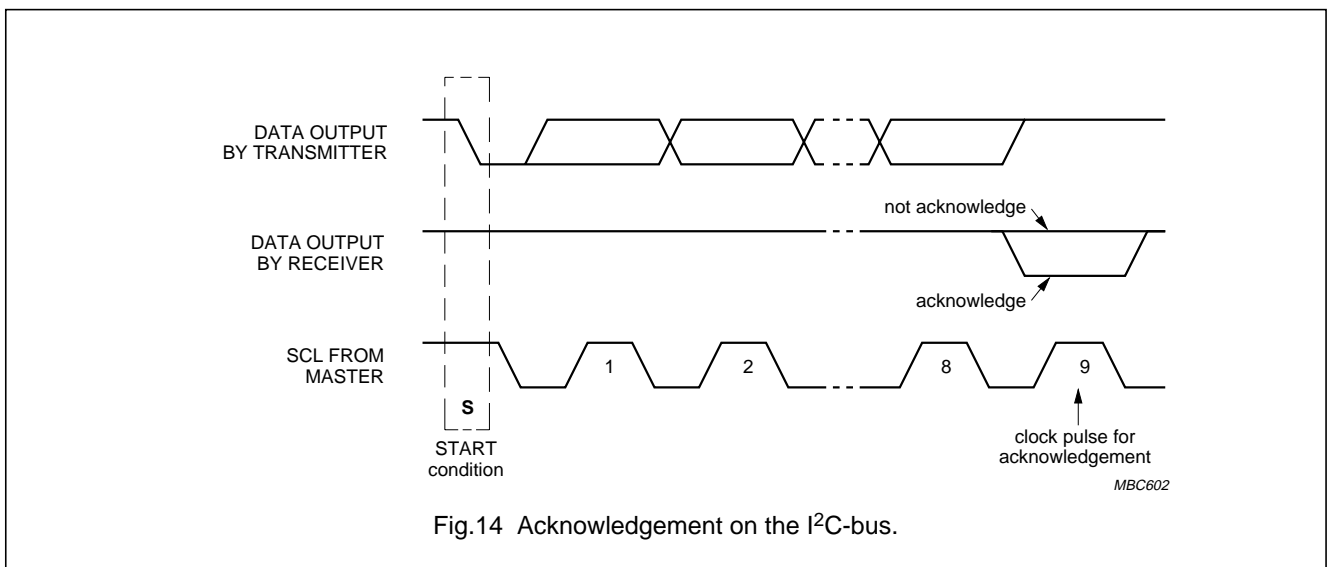


Fig.14 Acknowledgement on the I²C-bus.

8-bit A/D and D/A converter

PCF8591

8.5 I²C-bus protocol

After a start condition a valid hardware address has to be sent to a PCF8591 device. The read/write bit defines the direction of the following single or multiple byte data transfer. For the format and the timing of the start condition (S), the stop condition (P) and the acknowledge bit (A) refer to the I²C-bus characteristics. In the write mode a data transfer is terminated by sending either a stop condition or the start condition of the next data transfer.

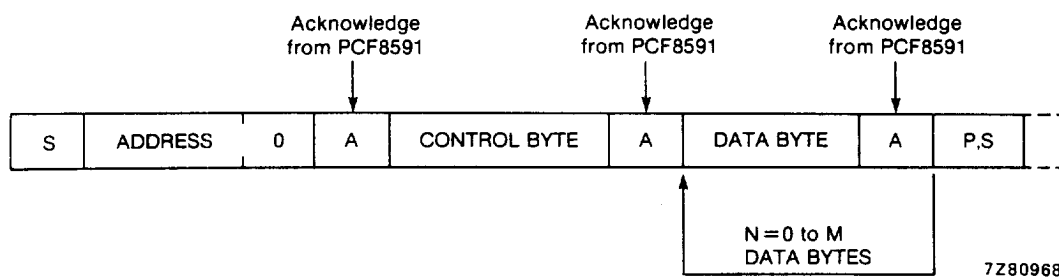


Fig.15 Bus protocol for write mode, D/A conversion.

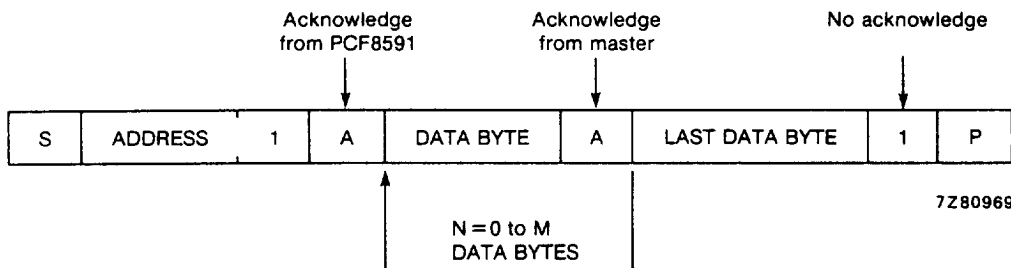


Fig.16 Bus protocol for read mode, A/D conversion.

8-bit A/D and D/A converter

PCF8591

9 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{DD}	supply voltage (pin 16)	-0.5	+8.0	V
V_I	input voltage (any input)	-0.5	$V_{DD} + 0.5$	V
I_I	DC input current	-	± 10	mA
I_O	DC output current	-	± 20	mA
I_{DD}, I_{SS}	V_{DD} or V_{SS} current	-	± 50	mA
P_{tot}	total power dissipation per package	-	300	mW
P_O	power dissipation per output	-	100	mW
T_{amb}	operating ambient temperature	-40	+85	°C
T_{stg}	storage temperature	-65	+150	°C

10 HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take precautions appropriate to handling MOS devices. Advice can be found in Data Handbook IC12 under "Handling MOS Devices".

8-bit A/D and D/A converter

PCF8591

11 DC CHARACTERISTICS

$V_{DD} = 2.5 \text{ V to } 6 \text{ V}$; $V_{SS} = 0 \text{ V}$; $T_{amb} = -40 \text{ }^\circ\text{C to } +85 \text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V_{DD}	supply voltage (operating)		2.5	–	6.0	V
I_{DD}	supply current					
	standby	$V_I = V_{SS}$ or V_{DD} ; no load	–	1	15	μA
	operating, AOUT off	$f_{SCL} = 100 \text{ kHz}$	–	125	250	μA
	operating, AOUT active	$f_{SCL} = 100 \text{ kHz}$	–	0.45	1.0	mA
V_{POR}	Power-on reset level	note 1	0.8	–	2.0	V
Digital inputs/output: SCL, SDA, A0, A1, A2						
V_{IL}	LOW level input voltage		0	–	$0.3 \times V_{DD}$	V
V_{IH}	HIGH level input voltage		$0.7 \times V_{DD}$	–	V_{DD}	V
I_L	leakage current					
	A0, A1, A2	$V_I = V_{SS}$ to V_{DD}	–250	–	+250	nA
	SCL, SDA	$V_I = V_{SS}$ to V_{DD}	–1	–	+1	μA
C_i	input capacitance		–	–	5	pF
I_{OL}	LOW level SDA output current	$V_{OL} = 0.4 \text{ V}$	3.0	–	–	mA
Reference voltage inputs						
V_{REF}	reference voltage	$V_{REF} > V_{AGND}$; note 2	$V_{SS} + 1.6$	–	V_{DD}	V
V_{AGND}	analog ground voltage	$V_{REF} > V_{AGND}$; note 2	V_{SS}	–	$V_{DD} - 0.8$	V
I_{LI}	input leakage current		–250	–	+250	nA
R_{REF}	input resistance	pins V_{REF} and $AGND$	–	100	–	$\text{k}\Omega$
Oscillator: OSC, EXT						
I_{LI}	input leakage current		–	–	250	nA
f_{OSC}	oscillator frequency		0.75	–	1.25	MHz

Notes

- The power on reset circuit resets the I²C-bus logic when V_{DD} is less than V_{POR} .
- A further extension of the range is possible, if the following conditions are fulfilled:

$$\frac{V_{REF} + V_{AGND}}{2} \geq 0.8 \text{ V}, V_{DD} - \frac{V_{REF} + V_{AGND}}{2} \geq 0.4 \text{ V}$$

8-bit A/D and D/A converter

PCF8591

12 D/A CHARACTERISTICS

$V_{DD} = 5.0\text{ V}$; $V_{SS} = 0\text{ V}$; $V_{REF} = 5.0\text{ V}$; $V_{AGND} = 0\text{ V}$; $R_L = 10\text{ k}\Omega$; $C_L = 100\text{ pF}$; $T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Analog output						
V_{OA}	output voltage	no resistive load	V_{SS}	–	V_{DD}	V
		$R_L = 10\text{ k}\Omega$	V_{SS}	–	$0.9 \times V_{DD}$	V
I_{LO}	output leakage current	AOUT disabled	–	–	250	nA
Accuracy						
OS_e	offset error	$T_{amb} = 25\text{ }^\circ\text{C}$	–	–	50	mV
L_e	linearity error		–	–	± 1.5	LSB
G_e	gain error	no resistive load	–	–	1	%
t_{DAC}	settling time	to $\frac{1}{2}$ LSB full scale step	–	–	90	μs
f_{DAC}	conversion rate		–	–	11.1	kHz
SNRR	supply noise rejection ratio	$f = 100\text{ Hz}$; $V_{DDN} = 0.1 \times V_{PP}$	–	40	–	dB

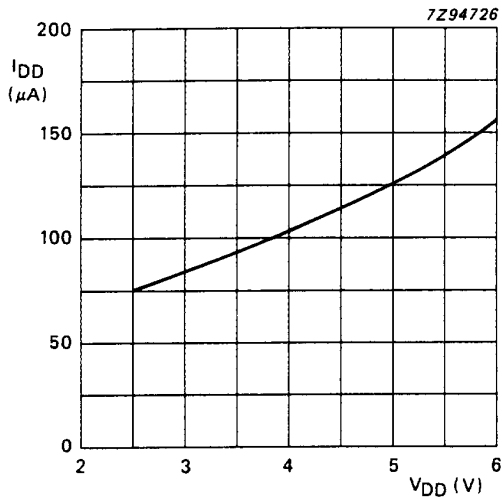
13 A/D CHARACTERISTICS

$V_{DD} = 5.0\text{ V}$; $V_{SS} = 0\text{ V}$; $V_{REF} = 5.0\text{ V}$; $V_{AGND} = 0\text{ V}$; $R_S = 10\text{ k}\Omega$; $T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$ unless otherwise specified.

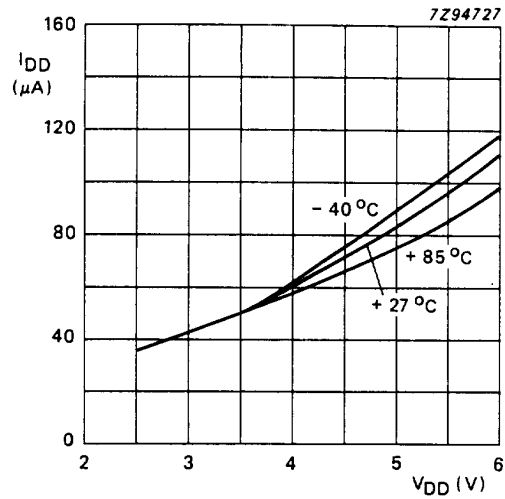
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Analog inputs						
V_{IA}	analog input voltage		V_{SS}	–	V_{DD}	V
I_{LIA}	analog input leakage current		–	–	100	nA
C_{IA}	analog input capacitance		–	10	–	pF
C_{ID}	differential input capacitance		–	10	–	pF
V_{IS}	single-ended voltage	measuring range	V_{AGND}	–	V_{REF}	V
V_{ID}	differential voltage	measuring range; $V_{FS} = V_{REF} - V_{AGND}$	$-\frac{V_{FS}}{2}$	–	$+\frac{V_{FS}}{2}$	V
Accuracy						
OS_e	offset error	$T_{amb} = 25\text{ }^\circ\text{C}$	–	–	20	mV
L_e	linearity error		–	–	± 1.5	LSB
G_e	gain error		–	–	1	%
GS_e	small-signal gain error	$\Delta V_i = 16\text{ LSB}$	–	–	5	%
CMRR	common-mode rejection ratio		–	60	–	dB
SNRR	supply noise rejection ratio	$f = 100\text{ Hz}$; $V_{DDN} = 0.1 \times V_{PP}$	–	40	–	dB
t_{ADC}	conversion time		–	–	90	μs
f_{ADC}	sampling/conversion rate		–	–	11.1	kHz

8-bit A/D and D/A converter

PCF8591

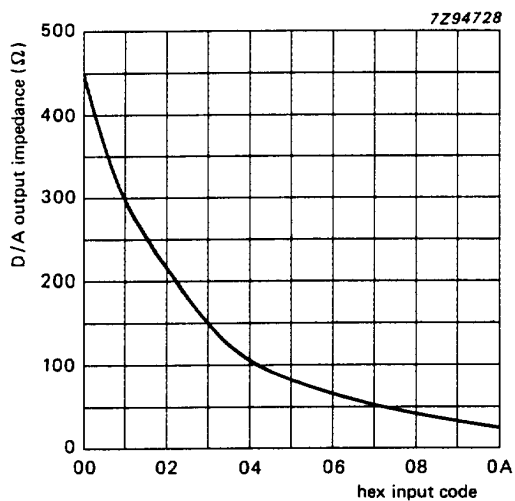


(a) Internal oscillator; $T_{amb} = +27\text{ }^{\circ}\text{C}$.

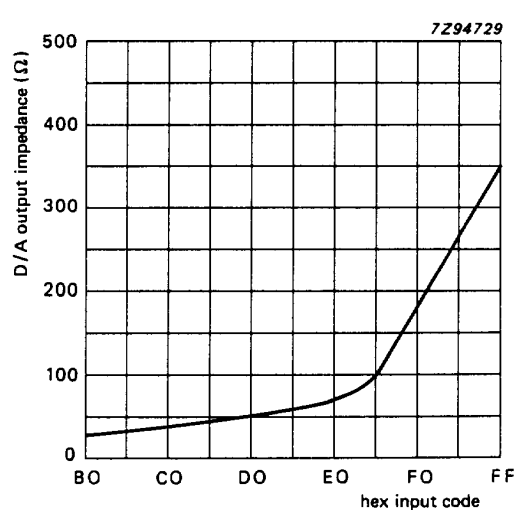


(b) External oscillator.

Fig.17 Operating supply current as a function of supply voltage (analog output disabled).



(a) Output impedance near negative power rail; $T_{amb} = +27\text{ }^{\circ}\text{C}$.



(b) Output impedance near positive power rail; $T_{amb} = +27\text{ }^{\circ}\text{C}$.

The x-axis represents the hex input-code equivalent of the output voltage.

Fig.18 Output impedance of analog output buffer (near power rails).

8-bit A/D and D/A converter

PCF8591

14 AC CHARACTERISTICS

All timing values are valid within the operating supply voltage and ambient temperature range and reference to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD} .

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
I²C-bus timing (see Fig.19; note 1)					
f_{SCL}	SCL clock frequency	–	–	100	kHz
t_{SP}	tolerable spike width on bus	–	–	100	ns
t_{BUF}	bus free time	4.7	–	–	μ s
$t_{SU;STA}$	START condition set-up time	4.7	–	–	μ s
$t_{HD;STA}$	START condition hold time	4.0	–	–	μ s
t_{LOW}	SCL LOW time	4.7	–	–	μ s
t_{HIGH}	SCL HIGH time	4.0	–	–	μ s
t_r	SCL and SDA rise time	–	–	1.0	μ s
t_f	SCL and SDA fall time	–	–	0.3	μ s
$t_{SU;DAT}$	data set-up time	250	–	–	ns
$t_{HD;DAT}$	data hold time	0	–	–	ns
$t_{VD;DAT}$	SCL LOW-to-data out valid	–	–	3.4	μ s
$t_{SU;STO}$	STOP condition set-up time	4.0	–	–	μ s

Note

1. A detailed description of the I²C-bus specification, with applications, is given in brochure "The I²C-bus and how to use it". This brochure may be ordered using the code 9398 393 40011.

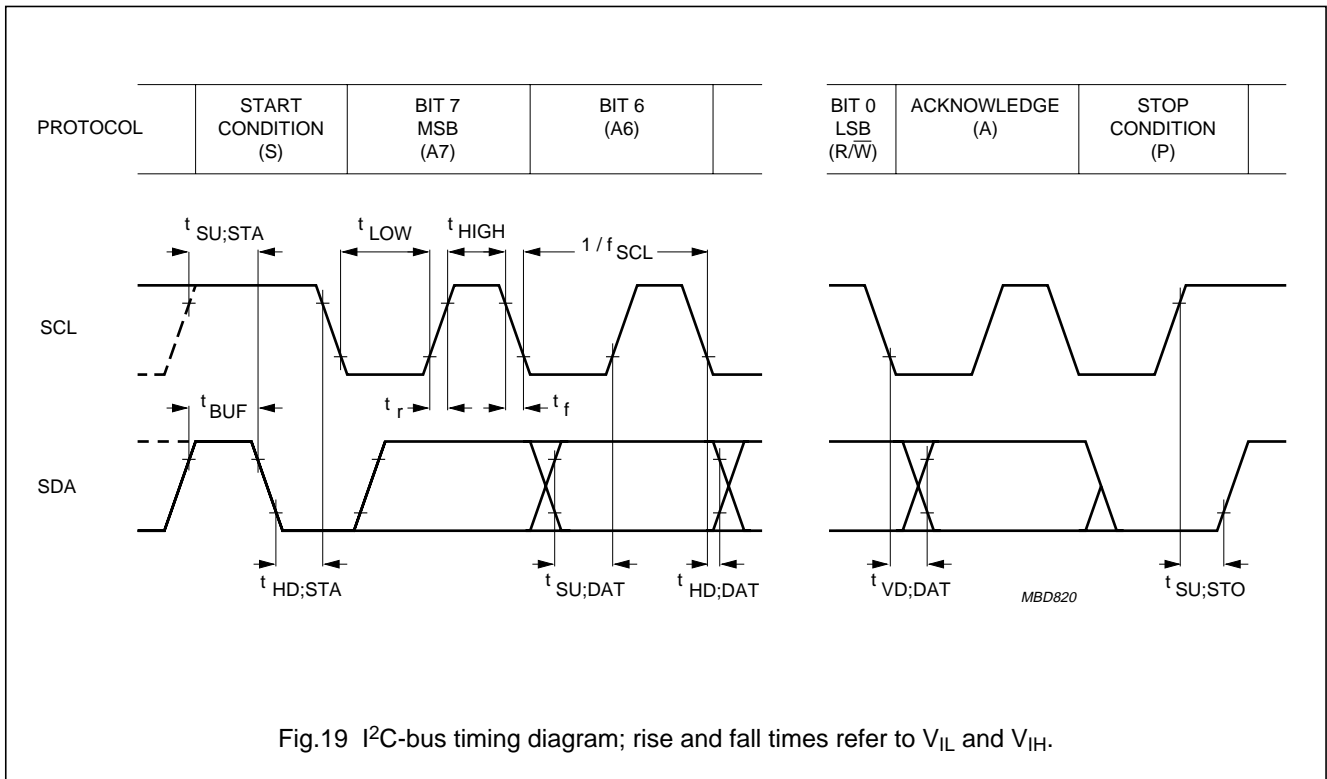


Fig.19 I²C-bus timing diagram; rise and fall times refer to V_{IL} and V_{IH} .

8-bit A/D and D/A converter

PCF8591

15 APPLICATION INFORMATION

Inputs must be connected to V_{SS} or V_{DD} when not in use. Analog inputs may also be connected to AGND or V_{REF} .

In order to prevent excessive ground and supply noise and to minimize cross-talk of the digital to analog signal paths the user has to design the printed-circuit board layout very carefully. Supply lines common to a PCF8591 device and noisy digital circuits and ground loops should be avoided. Decoupling capacitors ($>10 \mu\text{F}$) are recommended for power supply and reference voltage inputs.

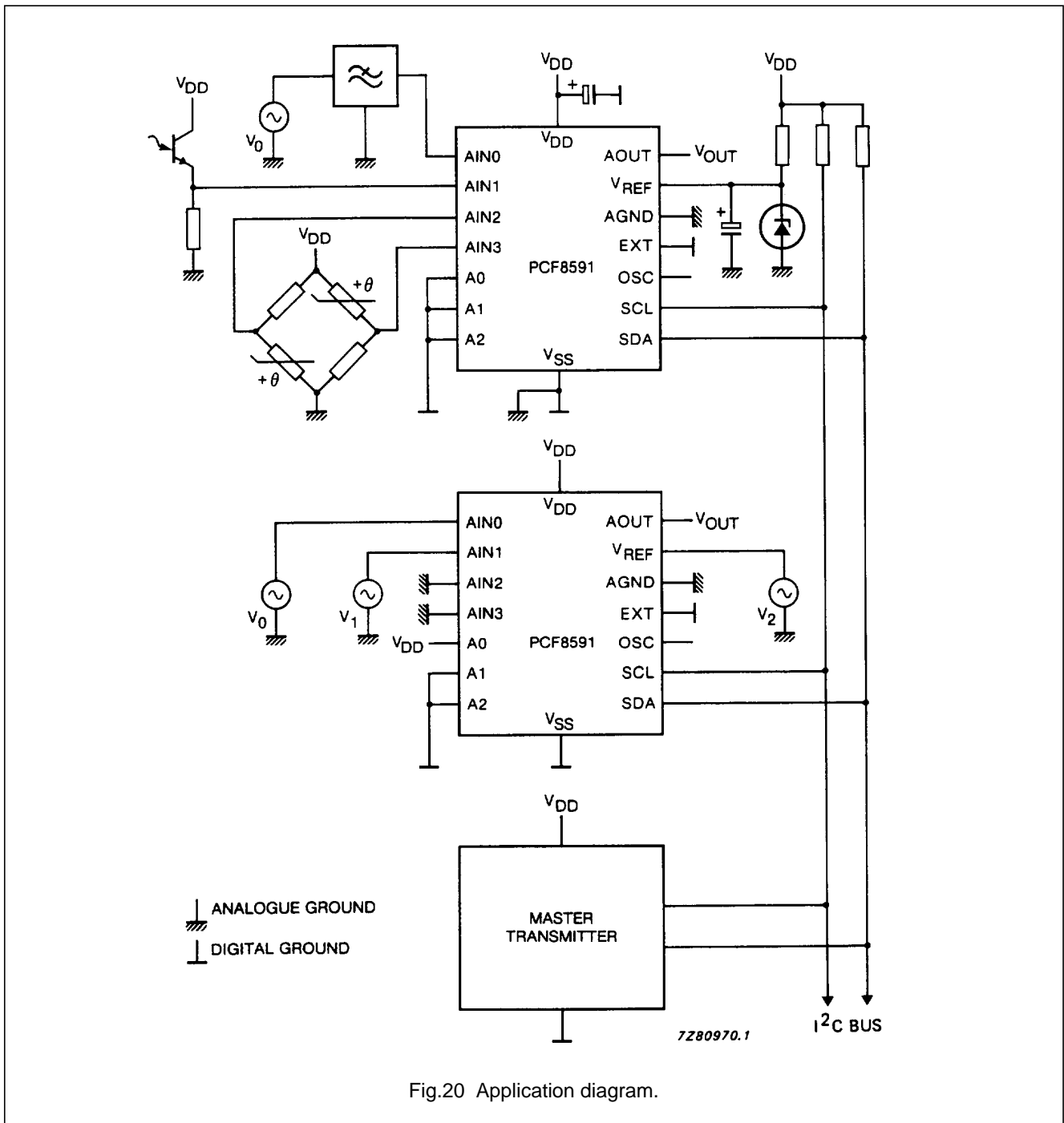


Fig.20 Application diagram.

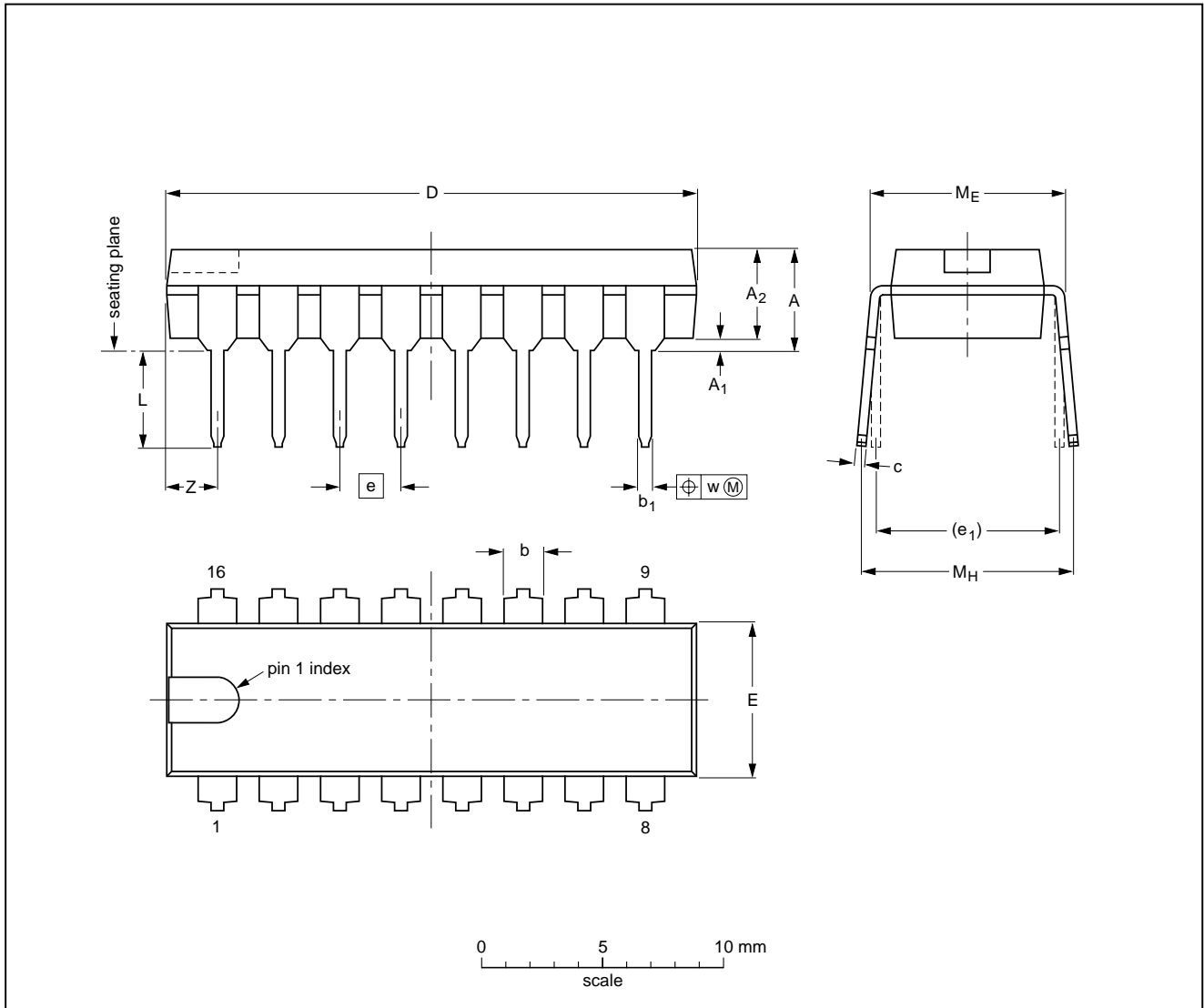
8-bit A/D and D/A converter

PCF8591

16 PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

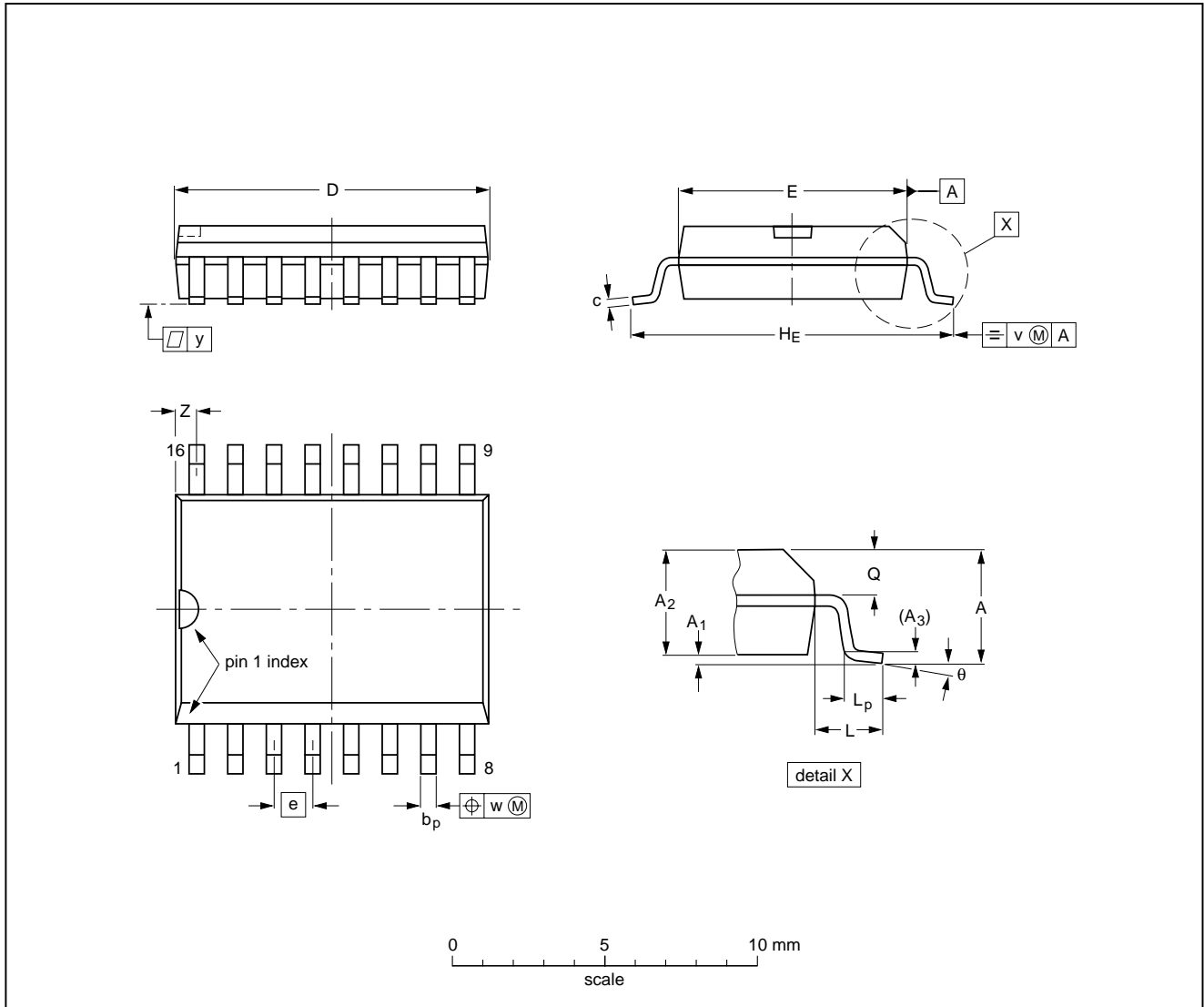
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02 95-01-19

8-bit A/D and D/A converter

PCF8591

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT162-1	075E03	MS-013AA			95-01-24 97-05-22

8-bit A/D and D/A converter

PCF8591

17 SOLDERING

17.1 Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (order code 9398 652 90011).

17.2 DIP

17.2.1 SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

17.2.2 REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

17.3 SO

17.3.1 REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

17.3.2 WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

17.3.3 REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

8-bit A/D and D/A converter

PCF8591

18 DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

19 LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

20 PURCHASE OF PHILIPS I²C COMPONENTS

Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

8-bit A/D and D/A converter

PCF8591

NOTES

8-bit A/D and D/A converter

PCF8591

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113, Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 160 1010, Fax. +43 160 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6, 220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor, 51 James Bourchier Blvd., 1407 SOFIA, Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS, Tel. +1 800 234 7381

China/Hong Kong: 501 Hong Kong Industrial Technology Centre, 72 Tat Chee Avenue, Kowloon Tong, HONG KONG, Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S, Tel. +45 32 88 2636, Fax. +45 31 57 0044

Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. +358 9 615800, Fax. +358 9 61580920

France: 51 Rue Carnot, BP317, 92156 SURESNES Cedex, Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG, Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS, Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Band Box Building, 2nd floor, 254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025, Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: PT Philips Development Corporation, Semiconductors Division, Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510, Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053, TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3, 20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905, Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341

Pakistan: see Singapore

Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA, Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW, Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 319762, Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale, 2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000, Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Al. Vicente Pinzon, 173, 6th floor, 04547-130 SÃO PAULO, SP, Brazil, Tel. +55 11 821 2333, Fax. +55 11 821 2382

Spain: Balmes 22, 08007 BARCELONA, Tel. +34 93 301 6312, Fax. +34 93 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM, Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH, Tel. +41 1 488 2741 Fax. +41 1 488 3263

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1, TAIPEI, Taiwan Tel. +886 2 2134 2865, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd., 209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260, Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL, Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7, 252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes, MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409, Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD, Tel. +381 11 625 344, Fax. +381 11 635 777

For all other countries apply to: Philips Semiconductors, International Marketing & Sales Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 1998

SCA60

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

415106/1200/04/pp28

Date of release: 1998 Jul 02

Document order number: 9397 750 04058

Let's make things better.

**Philips
Semiconductors**



PHILIPS